

Samtec Demonstrates Scalable Silicon Test Platform for AI Implementations at Xilinx Developer Forum

Demonstration Build Confidence in SI Performance in Next-Gen Architectures

SAN JOSE, Calif., Oct. 1, 2019 (Xilinx Developer Forum) - Samtec, a privately held \$812 MM global manufacturer of a broad line of electronic interconnect solutions, will demonstrate a Scalable 32 GT/s Silicon Test Platform for AI Implementations at the [Xilinx Developer Forum \(XDF\) 2019](#). XDF connects software developers and system designers to the deep expertise of Xilinx engineers, partners, and industry leaders.

Samtec high-speed technologies for Silicon-to-Silicon optimization will be on display, including new board-to-board and cable-to-board interconnects. 56 Gbps PAM4 product demonstrations and Samtec's expanding FMC/FMC+ ecosystem will also be highlighted.

Scalable Silicon Test Platform for AI Implementations

Confident SI evaluation in emerging AI forms factors and cable mesh topologies requires realistic interconnect stress. Current length extenders and multiple PCIe topologies present challenges for adequate SI evaluation.

Samtec will demonstrate the advantages of next-generation Scalable Silicon Test Platform for AI Implementations. The demonstration incorporates an AI-style interconnect based on the Gen-Z PECFF form factor. The topology incorporates up to eight risers that include PCIe Gen5 AI usage models and the Samtec [Flyover® Technology](#).

The demonstration couples 56Gbps PAM4 PBR31 data sourced from a Xilinx test chip containing GTM transceivers and a configurable system of next-generation interconnect. The test platform combines a cable mesh backplane ([AcceleRate® Slim Body Cable Assemblies](#)) and next-generation [High-Speed Edge Card Connector](#) topologies.

“Design and testing next-gen AI system architectures at 56 PAM4 and 32 GT/s data rates has many challenges,” said Matt Burns, Product Marketing Manager at Samtec, Inc. “Samtec’s new test platform simplifies their evaluation and development while building confidence in SI performance in the lab.”

For more information on the Scalable Silicon Test Platform for AI Implementations, please visit Samtec in Booth 19 at XDF. Additional technical details are available via [this blog](#).

More information about XDF is available at:

<https://www.xilinx.com/products/design-tools/developer-forum.html>. For additional updates from XDF, follow Xilinx on Twitter at [@XilinxInc](#) or via the hashtag [#XDF2019](#).

About Samtec, Inc.

Founded in 1976, Samtec is a privately held, \$822 MM global manufacturer of a broad line of electronic interconnect solutions, including High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Precision RF, Flexible Stacking, and Micro/Rugged components and cables. With 40+ locations serving approximately 125 countries, Samtec's global presence enables its unmatched customer service. For more information, please visit <http://www.samtec.com>.

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